

SEARAY™

(1,27 mm) .050"

SEAF-30-05.0-S-08-2-A-LP-K-TR

SEAF SERIES

HIGH SPEED/HIGH DENSITY OPEN PIN FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAF

Insulator Material:

Black LCP

Contact Mat

Copper Alloy
Operating Temp Range:
-55°C to +125°C

Current Rating
(7 mm stack height):

1.8 A per pin
(10 adjacent pins powered)

Plating:

Au or Sn over
50 μ" (1,27 μm) Ni

Contact Resistance: 5.5 mΩ

Working Voltage: 240 V

RoHS Compliant: Yes

RECOGNITIONS

For complete scope of
recognitions see
www.samtec.com/quality



FILE NO. E111594

Mates with:
SEAM, SEAMP,
SEAR, SEAMI, SEAC

Note: Patented

Note: Some sizes, styles and options are non-standard, non-returnable.

E.L.P.TM
EXTENDED LIFE PRODUCTS

10 year Mixed Flowing Gas with 30µ" Gold
Cell Sample for maximum rated cycles

Low /
insertion/
extraction
forces

Up to
500 pins

5, 8 and 10 row footprint
compatible with SamArray®.
Samples recommended.

Solder charges

SEAM/SEAF 10 mm Stack Height	Rated @ 3dB Insertion Loss
	w/o PCB effects*
Single-Ended Signaling	18 GHz / 36 Gbps
Differential Pair Signaling	18 GHz / 36 Gbps

*Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com?SEAF or contact sig@samtec.com

*Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com?SEAF or contact sig@samtec.com

SEAF **NO. PINS PER ROW** **LEAD STYLE** **PLATING OPTION** **NO. OF ROWS** **SOLDER TYPE** **A** **OPTION** **K** **TR**

LEAD STYLE

LEAD STYLE	A
-05.0	(5,05) .199
-06.0	(6,05) .238
-06.5	(6,55) .258

PLATING OPTION

PLATING OPTION	DESCRIPTION
-L	= 10 μ m (0,25 μ m) Gold on contact area, Matte Tin on solder tail
-S	= 30 μ m (0,76 μ m) Gold on contact area, Matte Tin on solder tail

NO. OF ROWS

NO. OF ROWS	DESCRIPTION
-04	= Four Rows
-05	= Five Rows
-06	= Six Rows
-08	= Eight Rows
-10	= Ten Rows

SOLDER TYPE

SOLDER TYPE	DESCRIPTION
-1	= Tin/Lead Alloy Solder Charge
-2	= Lead-Free Solder Charge

A **OPTION** **K** **TR**

OPTION	DESCRIPTION
-LP	= Latch Post (-LP required for SEAC mate only) (Available with -05.0 lead style and -04, -06, -08 & -10 rows only)
-K	= Polyimide film Pick & Place Pad (Not available with -10 and -15 pins with -LP Latch post)

TR

ALSO AVAILABLE (MOQ Required)

- Polarization pin
- Contact Samtec.

ALSO AVAILABLE
(MOQ Required)

- Polarization pin

Contact Samtec.

DIFFERENTIAL

MATED HEIGHTS			
SEAM LEAD STYLE	SEAF LEAD STYLE		
	-05.0	-06.0	-06.5
-02.0	7 mm	8 mm	8.5 mm
-03.0	8 mm	9 mm	9.5 mm
-03.5	8.5 mm	9.5 mm	10 mm
-06.5	11.5 mm	12.5 mm	13 mm
-07.0	12 mm	13 mm	13.5 mm
-09.0	14 mm	15 mm	15.5 mm
-11.0	16 mm	17 mm	17.5 mm

ARRAY	PAIR COUNT
50x10	125
50x8	100
40x10	100